

Product Specification: GE / IMI 7031 [02-33-001]

Low temperature glue for thermally anchoring wires at cryogenic temperatures. Does not outgas after baking and can be used in vacuum. Can be air-dried or baked.

Thermal Conductivity	
1K	0.034 W/m-K
4.2K	0.062 W/m-K
77K	0.22 W/m-K
100K	0.24 W/m-K
300K	0.44 W/m-K

Viscosity at 298K	1300cps
Specific gravity at 298K	0.89
Maximum operating temperature	423K
Flash point (TOC)	253K
Air drying time	10 minutes at RT
Baking time	2-5 minutes at 398K
Thinner	Ethanol or 50.50 ethanol:toluene
Evaporation rate (Butyl Acetate = 1)	Less than 1
Volume resistivity	1013-1015 Ω /cm